Customer Information Form

(SPRABZ9A – NOVEMBER 2015)

TEXAS INSTRUMENTS

IMPORTANT NOTES

*In order for Texas Instruments (TI) to provide verification and analysis services, all information as specified in this **"Customer Information Form"** (CIF) is required. Incomplete, unclear and or inaccurate information may result in the delay of analysis as well as the limited depth of the analysis. Customers who do not purchase directly from TI, must first involve their distributor to resolve issues and return TI part(s) via the distribution channel in order to comply with the distributor' business & return process.*

TI will not provide verification and analysis services for parts purchased through unauthorized sources (brokers, independent distributors, or 3rd party test houses) due to the uncertainties concerning product custody and the supply chain through which such parts may have been obtained. Furthermore, TI will not provide warranty coverage for any device purchased through unauthorized sources. TI is strengthening our customer return policies to help ensure our authorized supply chain is free of counterfeit and untrustworthy material. TI is committed to keeping TI products out of unauthorized channels, as well as identifying and stopping counterfeiting of TI products. We appreciate your support in helping us maintain a secure supply chain by providing all of the requested information.

*Email an electronic copy of this "**Customer Information Form"** (CIF) to your distributor and your Texas Instruments contact. Please print a hard copy and include with the sample return shipment. The most current of the **"Guidelines for adequate Customer Return Handling"** apply.*

Ship to Address: *This is the dedicated shipping address of the TI site doing initial verification / analysis.*	

Customer Reference/Tracking #:	
Sales Order Number (SO#)	
Delivery Document Number (DN#)	
Purchase Order Number (PO#)	

Customer Contact: *Please fill in your contact information in case additional information is required for TI verification and/or to share the TI reports.*	Company Name:	
	Contact Person:	
	Address:	
	Phone:	
	E-Mail:	
Sales Channel: *First involve the distributor as your business partner to align with the distributor return process.*	☐ Parts were bought directly from Texas Instruments.	
	TI Sales Contact Name:	
	TI Sales Contact E-Mail Address:	
	☐ Parts were bought from a TI authorized Distributor.	
	Distributor Name:	
	Distributor Site / Location:	
	Distributor Contact E-Mail Address:	
	Distributor RMA# / SCAR#	
Board Manufacturer: *In the case of a 3rd party manufacturing the boards.*	☐ No board manufacturer (EMSI) is used.	
	☐ Yes, a Board Manufacturer (EMSI) is used.	
	Board Manufacturer Name:	
	Board Manufacturer Site / Location:	
	Board Manufacturer E-Mail Address:	

Customer Priority: *How urgent is this analysis?*	☐ **Standard:** *Manufacturing is inconvenienced* *Increase in field fallout* *Minor issue with product*	☐ **Major:** *Field fallout level of concern* *Major impact on throughput* *Production Stop*	☐ **Critical:** *Prevents product shipment* *Unacceptable field reliability* *Severely impacts product*

Customer Application:

☐ Consumer	☐ Computer	☐ Automotive
☐ Industrial	☐ Avionics / Military / Space	☐ Other *(please specify!)*
☐ Telecom	☐ Medical	

Customer Detection Place:

☐ Incoming Inspection	☐ Prototype	☐ 0 km / 0 hrs
☐ Reliability / Qual Test	☐ Production / Assembly	☐ Field Failure [mile / km]
☐ In-Circuit Test (ICT)	☐ System Level Test	☐ Other *(please specify!)*
☐ Functional Test (FCT)	☐ Application	

Type of Issue:

Electrical:	**Visual / Mechanical:**	**Shipping:**
☐ Functional Issue	☐ Carrier (T&R, tube or tray)	☐ Damaged Carton/Box
☐ Parametric Issue	☐ Pin(s) / Ball(s) Condition	☐ Labeling
☐ Open / Short Circuit	☐ Package Damage	☐ Incomplete Seal
☐ Impedance Measurement	☐ TI Part Marking	☐ Wrong TI Part / Quantity
☐ Programming Issue ***Additional Questionnaire!***	☐ Solderability Issue ***Additional Questionnaire!***	☐ Document Missing
☐ Memory (RAM/Flash)	**Other:** *(please specify!)*	

Product Details:

Texas Instruments Part Number (P/N):		Customer Part Number (CP/N):	
Total Failed Quantity:		Total Ordered Quantity:	
Failure Rate:		Suspect Lot Trace Code:	
Returned Quantity:		Suspect Ship Trace Code:	

	Suspect TI Part Marking: *(top and backside - please attach pictures, if available)*	Good TI Part Marking: *(top and backside - please attach pictures, if available)*
Top Side Marking		
Backside Marking		

Customer Failure Conditions:

Temperature [°C]	Frequency [f]	Vcc / Vdd [V]	Vout [V]

Issue Details and Description:

TI needs detailed information in order to duplicate the issue on a stand-alone TI part in the lab.
***Important:* Please provide schematics of the circuit along with measurement results & wave forms separately by email!**

Failure Isolation & Application Information from the Customer:

What is the condition of the suspected failing TI part(s)?	☐ Repeatable	☐ Sporadic
Was the observed issue verified on TI part level outside the application?		☐ Yes / ☐ No
Did replacing the suspect TI part with a new TI part resolve the issue?		☐ Yes / ☐ No
Was the suspect TI part installed onto another passing board causing that board to fail (A-B-A swap)? Means did the failure follow the suspect TI part? *This is an essential part of the troubleshooting analysis. Pls ensure this has been performed!*		☐ Yes / ☐ No
Is the suspect TI part used in more than one location on the circuit board?		☐ Yes / ☐ No
If yes, how many locations?		
Which locations are causing the issue?		
Is this a new application?		☐ Yes / ☐ No
When was TI part designed into this application?		
Was the application/design changed or modified recently?		☐ Yes / ☐ No
Did the same issue occur in the past?		☐ Yes / ☐ No
If yes, please provide the reference TI QTS# or National PQA#.		

Programmable Products

Is the TI part protected by a Security Key Code? ☐ Yes / ☐ No

Which Firmware Version is used?

Low-Power RF (Chipcon) Radio Products

TI Part Register Settings?

MSP430™ Ultra-Low Power 16-Bit Microcontrollers:

JTAG access? ☐ Yes / ☐ No

Security fuse blown? If yes please provide the customer code! ☐ Yes / ☐ No

In case a FRAM TI part needs to be replaced on an application board the customer must be aware that the memory content can be changed by the de-soldering process. Therefore it is recommended to analyze any wrong application behavior directly on the application board or read out the memory content of the TI part before de-soldering.

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In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

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